

SOT835-1

plastic thermal enhanced ball grid array package; 672 balls;
body 40 x 40 x 1.2 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA672
Package type industry code	HBGA672
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-11-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	39.8	-	40	40.2	mm
E	package width	39.8	-	40	40.2	mm
A	seated height	[tbd]	-	1.85	1.85	mm
A ₂	package height	1.15	-	1.2	1.35	mm
n ₂	actual quantity of termination	-	-	672	-	

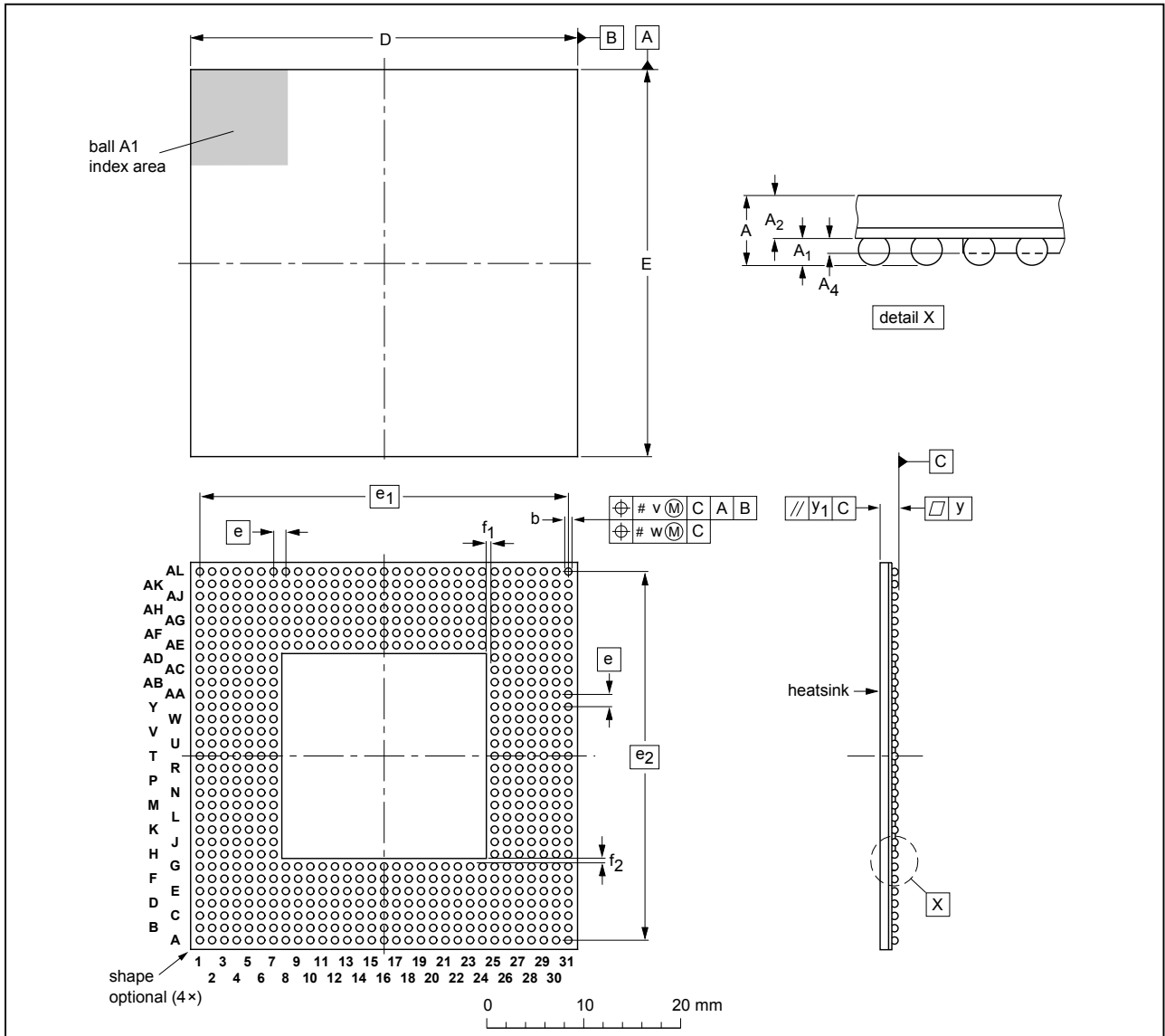


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2. Package outline

HBGA672: plastic thermal enhanced ball grid array package; 672 balls;
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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₄ max.	b	D	E	e	e ₁	e ₂	v	w	y	y ₁	f ₁ min.	f ₂ min.
mm	1.85	0.7 0.6	1.35 1.15	0.42	0.85 0.65	40.2 39.8	40.2 39.8	1.27	38.1	38.1	0.3	0.1	0.15	0.15	0.5	0.5

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT835-1	---	MS-034	---			03-11-18

Fig. 1. Package outline HBGA672 (SOT835-1)

3. Soldering

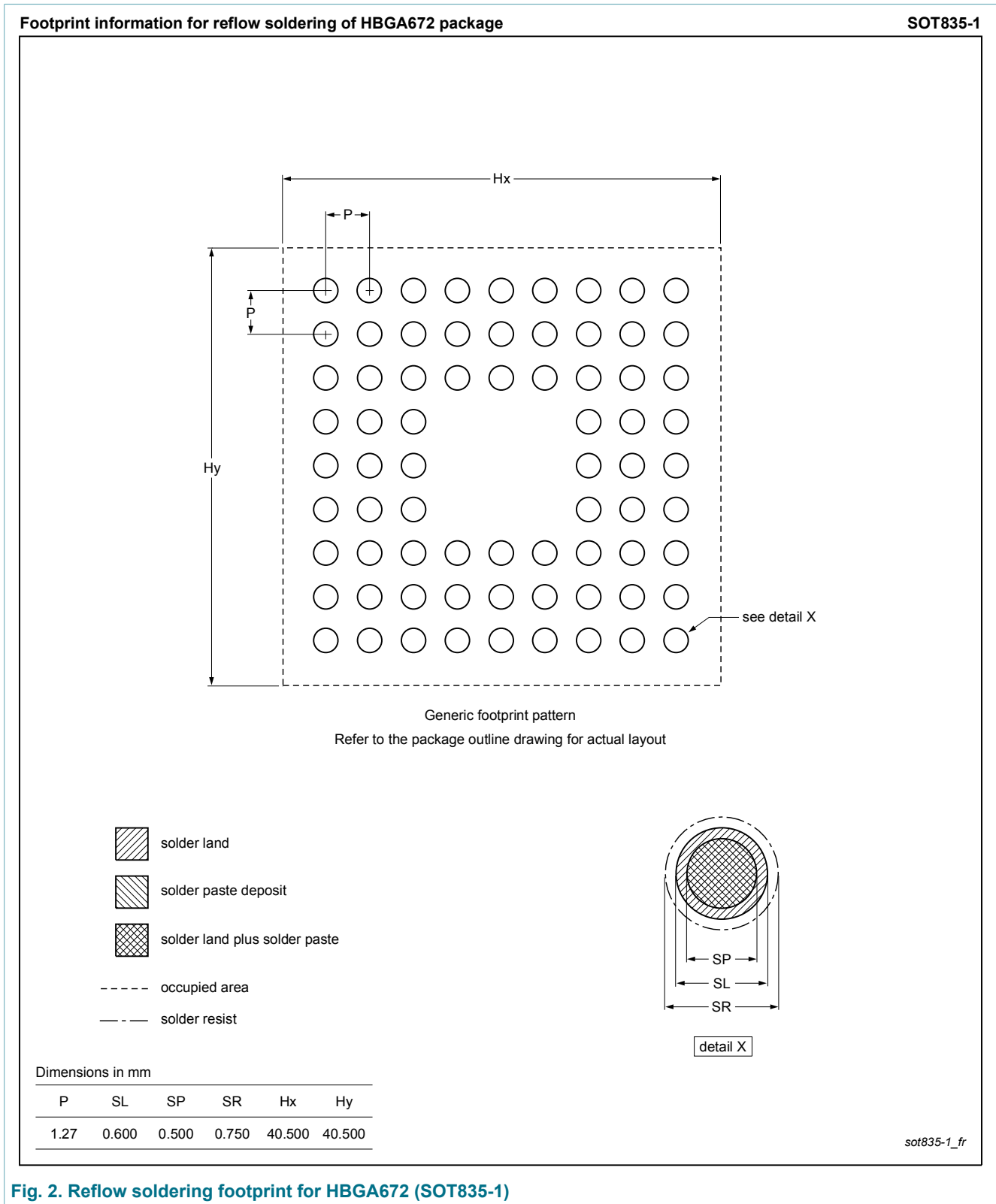


Fig. 2. Reflow soldering footprint for HBGA672 (SOT835-1)

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4. Legal information

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